



#### **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	I <sub>D</sub> Max T <sub>A</sub> = +25°C		
-60V	28mΩ @ V <sub>GS</sub> = -10V	-7A		
-000	$35m\Omega @ V_{GS} = -4.5V$	-6.2A		

# **Description and Applications**

This MOSFET is designed to minimize the on-state resistance  $(R_{DS(ON)})$  and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Backlighting
- Power Management Functions
- DC-DC Converters

#### 60V P-CHANNEL ENHANCEMENT MODE MOSFET

#### **Features and Benefits**

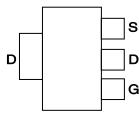
- Low On-Resistance
- Fast Switching Speed
- Low Threshold
- Low Gate Drive
- Low Input Capacitance
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

### **Mechanical Data**

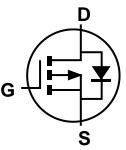
- Case: SOT223
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See Diagram Below
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.112 grams (Approximate)



Top View



Pin Out - Top View



Equivalent Circuit

#### Ordering Information (Note 5)

Part Number	Case	Packaging
DMP6023LEQ-13	SOT223	2,500/Tape & Reel

Notes:

1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.

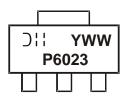
2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to http://www.diodes.com/product\_compliance\_definitions.html.

5. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

# **Marking Information**



 $D_{++}^{++}$  = Manufacturer's Marking P6023 = Marking Code YWW = Date Code Marking Y or Y = Year (ex: 7 = 2017) WW = Week (01 to 53)



# Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	V <sub>DSS</sub>	-60	V	
Gate-Source Voltage		V <sub>GSS</sub>	±20	V
Continuous Drain Current (Note $\sum 1/2$ 40)/	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	ID	-7 -5.6	А
Continuous Drain Current (Note 5) V <sub>GS</sub> = -10V	T <sub>C</sub> = +25°C T <sub>C</sub> = +70°C	ID	-18.2 -14.5	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I <sub>DM</sub>	-50	А	
Maximum Continuous Body Diode Forward Current (Note 5)	Is	-2	А	
Avalanche Current, L = 0.1mH	I <sub>AS</sub>	-35.5	А	
Avalanche Energy, L = 0.1mH	E <sub>AS</sub>	62.9	mJ	

# **Thermal Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	PD	2 1.3	W
Thermal Resistance, Junction to Ambient (Note 5)		$R_{ extsf{ heta}JA}$	60	°C/W
Total Power Dissipation (Note 5)	$T_{\rm C}$ = +25°C	PD	17.3	W
Thermal Resistance, Junction to Case (Note 5)		R <sub>θ</sub> JC	7.2	°C/W
Operating and Storage Temperature Range		T <sub>J,</sub> T <sub>STG</sub>	-55 to +150	°C

### Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

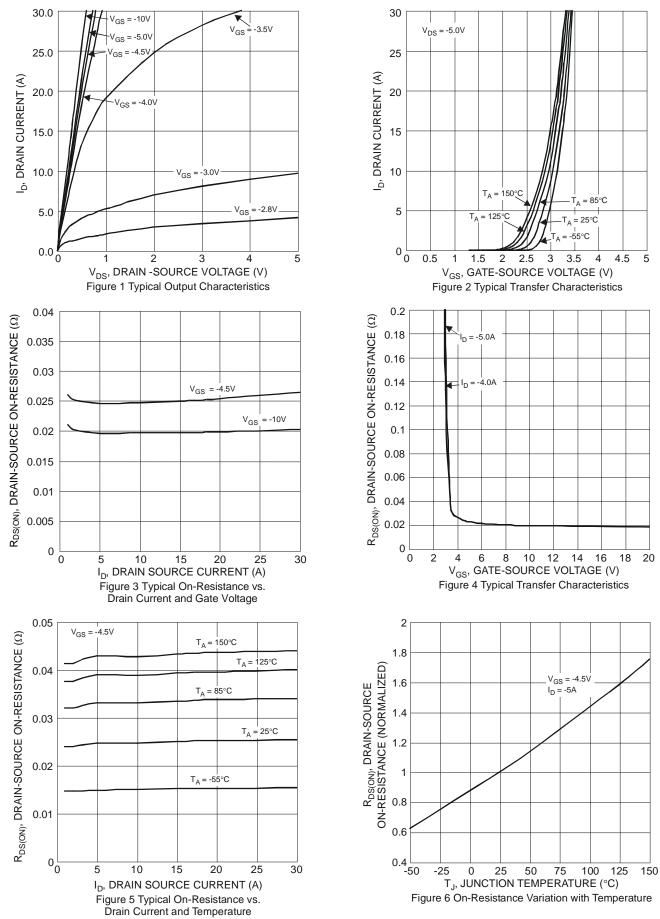
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 6)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-60	—	—	V	$V_{GS} = 0V, I_D = -250\mu A$	
Zero Gate Voltage Drain Current TJ = +25°C	I <sub>DSS</sub>	_	—	-1	μA	$V_{DS} = -60V, V_{GS} = 0V$	
Gate-Source Leakage	I <sub>GSS</sub>	_	—	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 6)						·	
Gate Threshold Voltage	V <sub>GS(TH)</sub>	-1		-3	V	$V_{DS} = V_{GS}$ , $I_D = -250 \mu A$	
Static Drain-Source On-Resistance	<b>D</b>	—		28	mΩ	$V_{GS} = -10V, I_D = -5A$	
	R <sub>DS(ON)</sub>	_		35		$V_{GS} = -4.5V, I_D = -4A$	
Diode Forward Voltage	V <sub>SD</sub>	_	-0.7	-1.2	V	$V_{GS} = 0V, I_{S} = -1A$	
DYNAMIC CHARACTERISTICS (Note 7)	•					·	
Input Capacitance	Ciss	—	2569	—	pF		
Output Capacitance	Coss	_	179	_	pF	− V <sub>DS</sub> = -30V, V <sub>GS</sub> = 0V, − f = 1MHz	
Reverse Transfer Capacitance	C <sub>rss</sub>	_	143	_	pF		
Gate Resistance	Rg	_	8	—	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$	
Total Gate Charge (V <sub>GS</sub> = -4.5V)	Qg	_	26.5	—	nC		
Total Gate Charge (V <sub>GS</sub> = -10V)	Qg	_	53.1	—	nC		
Gate-Source Charge	Q <sub>gs</sub>	_	7.1	_	nC	$V_{DS} = -30V, I_D = -5A$	
Gate-Drain Charge	Q <sub>gd</sub>	_	12.6	—	nC	7	
Turn-On Delay Time	t <sub>D(ON)</sub>	_	6	_	ns		
Turn-On Rise Time	t <sub>R</sub>	_	7.1		ns	$V_{GS} = -10V, V_{DS} = -30V,$	
Turn-Off Delay Time	t <sub>D(OFF)</sub>	_	110	_	ns	$R_g = 3\Omega, I_D = -5A$	
Turn-Off Fall Time	tF		62		ns	7	
Body Diode Reverse Recovery Time	t <sub>RR</sub>	_	20	_	ns		
Body Diode Reverse Recovery Charge	Q <sub>RR</sub>	_	14	—	nC	- I <sub>F</sub> = -5A, di/dt = 100A/μs	

5. Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square pad layout. Notes:

6. Short duration pulse test used to minimize self-heating effect. 7. Guaranteed by design. Not subject to product testing.

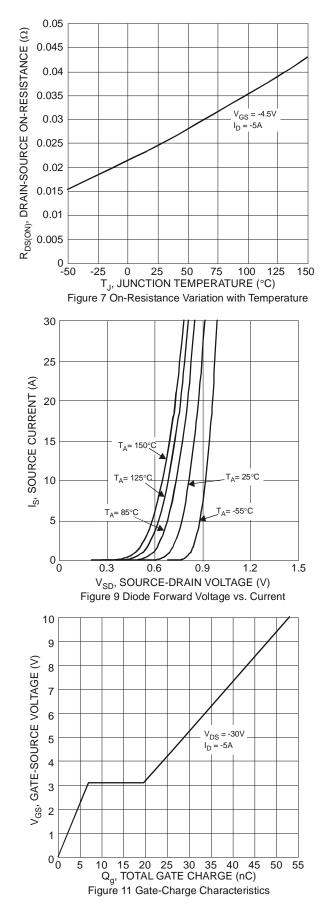


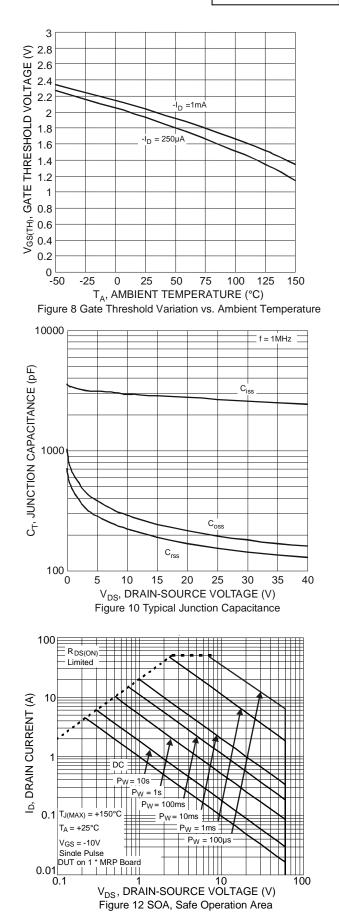
### DMP6023LEQ



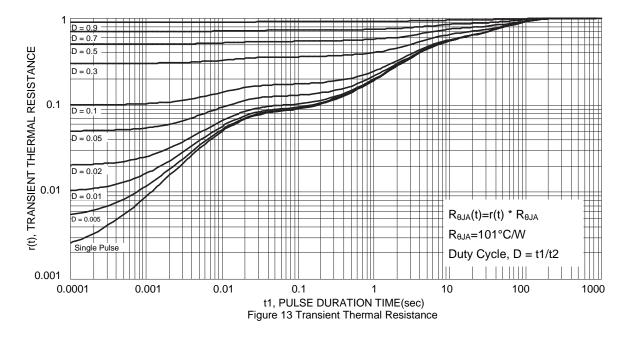
DMP6023LEQ Document number: DS39935 Rev. 1 - 2







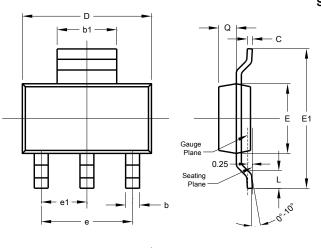


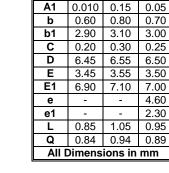




# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.





Dim

Α

SOT223

Max

1.65

Тур

1.60

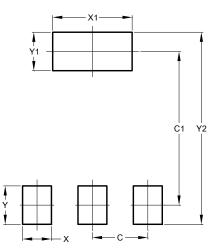
Min

1.55

# Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### SOT223



Dimensions	Value (in mm)
С	2.30
C1	6.40
Х	1.20
X1	3.30
Y	1.60
Y1	1.60
Y2	8.00



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